

RGP10A - RGP10M

Features

- 1.0 ampere operation at $T_A = 55^\circ\text{C}$ with no thermal runaway.
- High temperature metallurgically bonded construction.
- Glass passivated cavity-free junction.
- Typical I_R less than $1\mu\text{A}$.
- Fast switching for high efficiency.



DO-41
COLOR BAND DENOTES CATHODE

1.0 Ampere Glass Passivated Fast Recovery Rectifiers

Absolute Maximum Ratings*

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$I_{F(AV)}$	Average Rectified Current .375 " lead length @ $T_L = 55^\circ\text{C}$	1.0	A
I_{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms single half-sine-wave Superimposed on rated load (JEDEC method)	30	A
P_D	Total Device Dissipation Derate above 25°C	2.5 17	W mW/ $^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	$^\circ\text{C}/\text{W}$
T_{stg}	Storage Temperature Range	-65 to +175	$^\circ\text{C}$
T_J	Operating Junction Temperature	-65 to +175	$^\circ\text{C}$

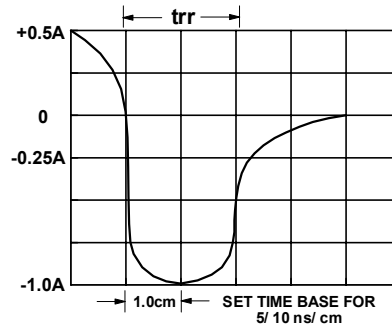
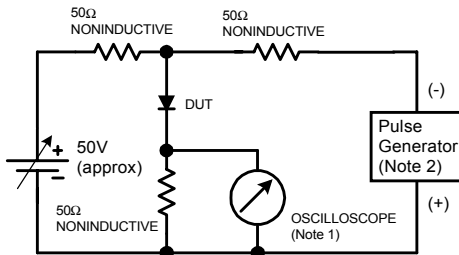
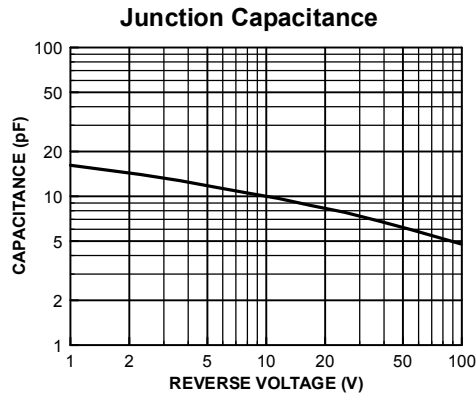
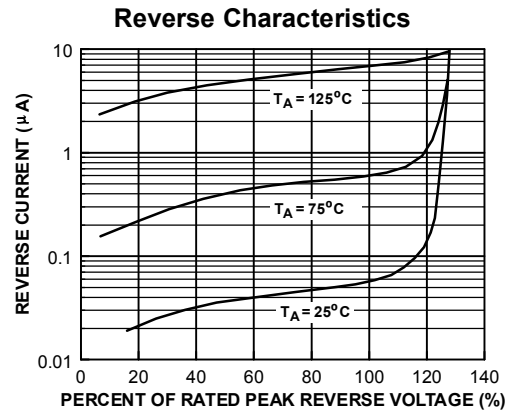
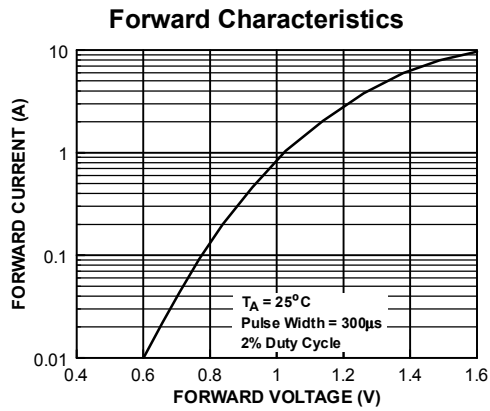
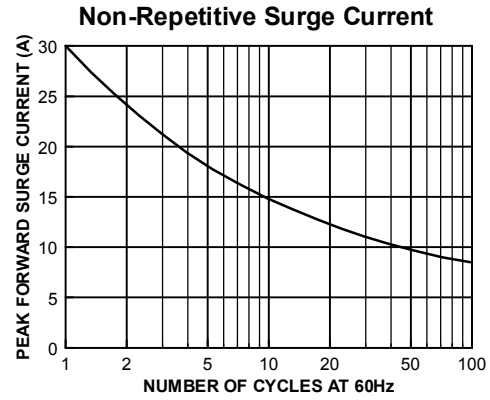
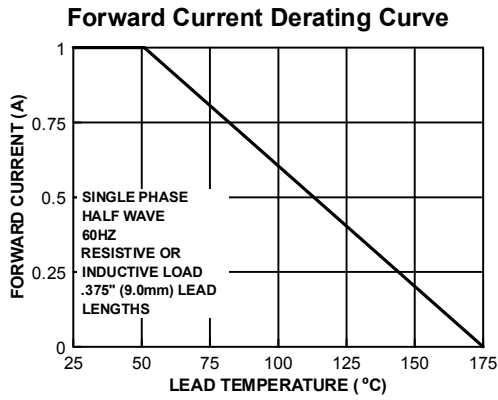
*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Device							Units
		10A	10B	10D	10G	10J	10K	10M	
V _{RRM}	Maximum Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
V _{RMS}	Maximum RMS Voltage	35	70	140	280	420	560	700	V
V _R	DC Reverse Voltage (Rated V _R)	50	100	200	400	600	800	1000	V
I _R	Maximum Instantaneous Reverse Current @ rated V _R T _A = 25°C T _A = 150°C	5.0 200							μA μA
t _{rr}	Maximum Instantaneous Reverse Recovery Time I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A	150				250	500		ns
V _{FM}	Maximum Forward Voltage @ 1.0 A	1.3							V
C	Typical Junction Capacitance V _R = 4.0 V, f = 1.0 MHz	15							pF

Typical Characteristics

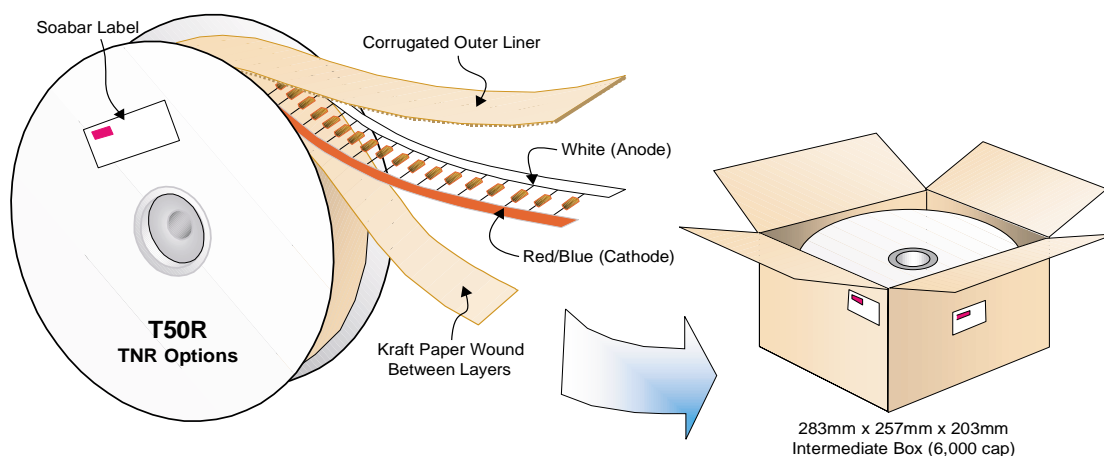


Reverse Recovery Time Characteristic and Test Circuit Diagram

DO-41 (Glass) Tape and Ammo Data



DO-41 (Glass) Packaging Configuration: Figure 1.0



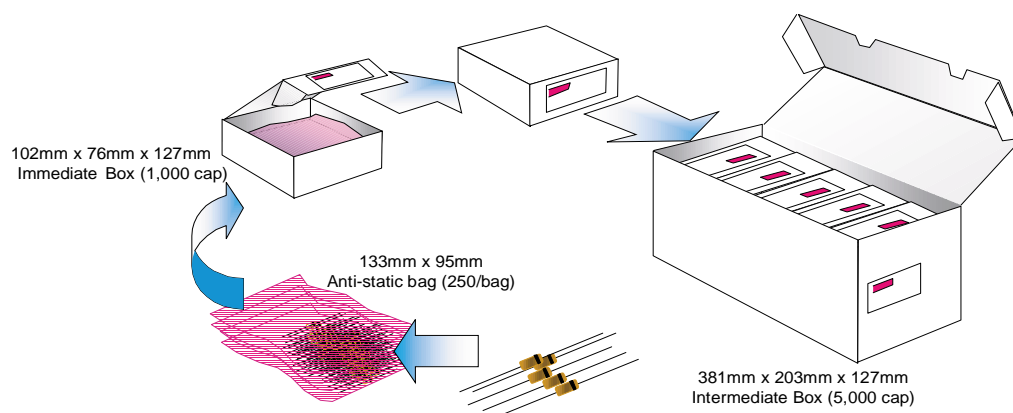
DO-41 (Glass) Packaging Information Table : Figure 2.0

DO-41 (Glass) Packaging Information			
Packaging Option	T50R	T50A	Standard (no flow code)
Packaging type	TNR	Ammo	Bag
Qty per Reel/Tube/Bag	3,000	3,000	250
Reel Size (inch diameter)	10.5	-	-
Inside Tape Spacing (mm)	52	52	-
Int Box Dimension (mm)	283x257x203	406x267x184	381x203x127
Max qty per Box	6,000	30,000	5,000
Weight per unit (gm)	0.320	0.320	0.320
Weight per Reel (kg)	1.356	1.077	-
Note/Comments			Bulk

Soabar Label sample

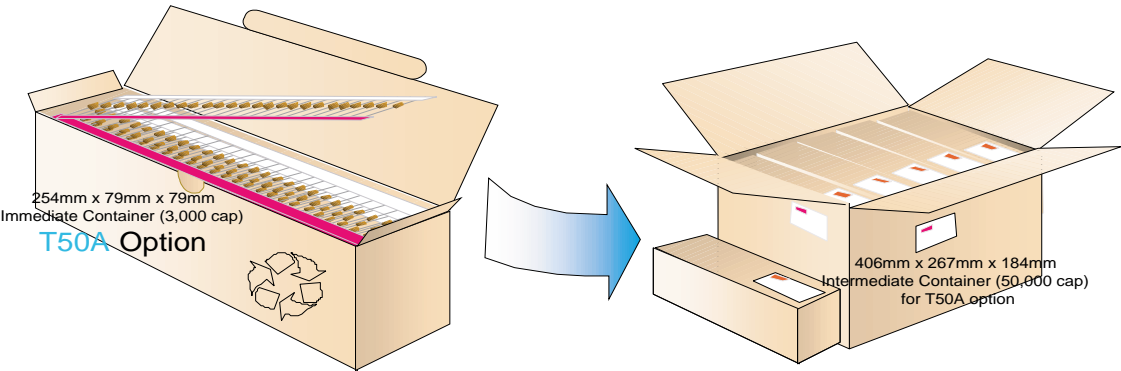
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TYPE	1N4744A	MARK	BLK-BRN
REV	A2	PART No.	
PKG		EC No.	
QTY	3,000	M.O. No.	OX5046F035
Q.C.		DATE	D9903
MFD. UNDER US PAT 3,025,589 & OTHER US PATS & APPLICATIONS			

DO-41 (Glass) Bulk Packing Configuration: Figure 3.0

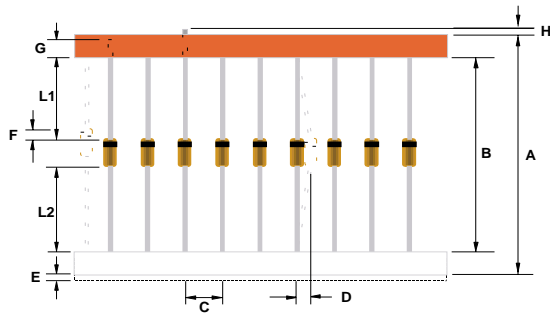


DO-41 (Glass) Tape and Ammo Data, continued

DO-41 (Glass) Ammo Packing Configuration: Figure 4.0



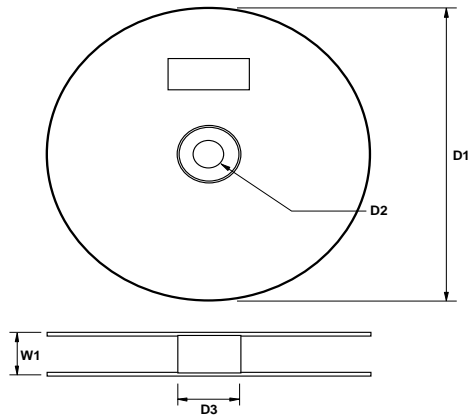
DO-41 (Glass) Taping Dimension: Figure 5.0



TAPING DIMENSIONS

	INCH	MM	MILS	NOTES
A	2.520 +0.066/ -0.027	64.00 +1.69/ -0.69	2519 +66.5/ -27.0	Overall width
B	2.047±0.027	52 ±0.69	2047±27	Inside Tape Spacing
C	0.200 ±0.0157	5.08 ±0.40	200 ±15.7	Component Pitch
D	0.047(max)	1.2(max)	47(max)	Component Misalignment
E	0.022(max)	0.55(max)	22(max)	Tape Mismatch
F	0.027(max)	±0.69	±27	Units in line w/ one another
G	0.126(min)	3.2(min)	126(min)	Lead amount between tapes
H	0	0	0	Lead amount beyond tapes
L1-L2	±0.027	±0.69	±27	Delta between two leads

DO-41 (Glass) Reel Dimension: Figure 6.0



REEL DIMENSIONS

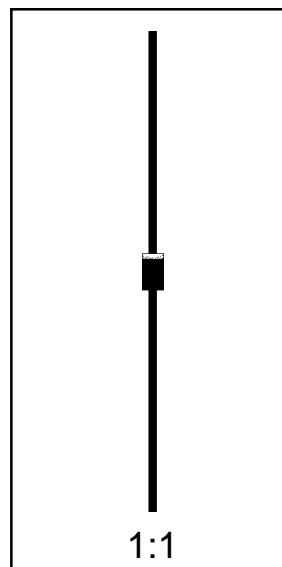
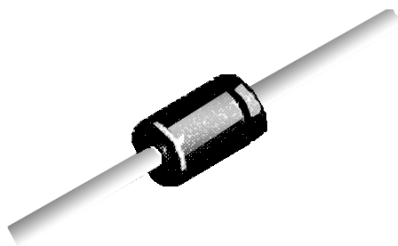
ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	10.375	10.625
Arbor Hole Diameter (Standard)	D2	1.245	1.255
Core Diameter	D3	3.190	3.310
Flange to Flange Outer Width	W1		3.400

Note: All Dimensions are in inches

DO-41 (Glass) Package Dimensions



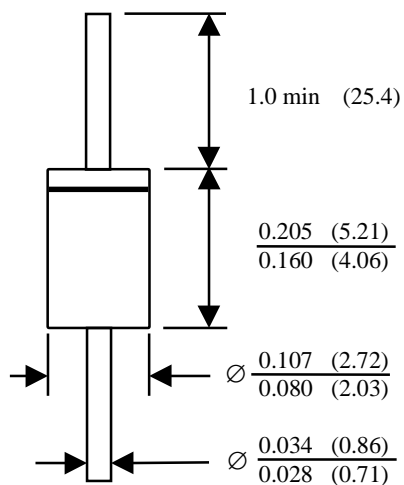
DO-41 (FS PKG Code D4)



Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.32



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